

Technical data sheet



Product: 567

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SYLGARD™ 567 PRIMERLESS SILICONE ENCAPS.

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**SYLGARD™ 567 Primerless Silicone Encapsulant**

Two-part, heat cure, 1 to 1 mix, black encapsulant with good flame resistance.

Features & Benefits

- 1 to 1 mix ratio
- Flowable
- Self-priming
- UL 94 V-0 Recognized
- No additional priming step required
- Rapid, versatile cure processing controlled by temperature
- Low viscosity enhances flow and fill in narrow spaces and around complex geometries
- Good dielectric properties

Composition

- Two-part, primerless silicone encapsulant kit

Applications

SYLGARD™ 567 Primerless Silicone Encapsulant is suitable for:

- General potting applications in applications like power supplies, automotive assembly, LED lighting, connectors, industrial controls, amplifiers, relays and high voltage resistor packs
- Encapsulant for solar cells

Typical Properties

Specification Writers: These values are not intended for use in preparing specifications.

Property	Unit	Result
One or Two Part		Two
Color		Black
Viscosity (Part A)	cP	2060
	Pa-sec	2.06
Viscosity (Part B)	cP	570
	Pa-sec	0.57
Thermal Conductivity	BTU/hr ft °F	0.17
	W/m °K	0.29
Specific Gravity (Uncured)		1.24
Heat Cure Time at 70°C	minutes	180
Heat Cure Time at 100°C	minutes	120

Typical Properties (Cont.)

Property	Unit	Result
Durometer Shore A		40
Dielectric Strength	volts/mil	405
	kV/mm	16
Volume Resistivity	ohm *cm	6x10 ¹⁶
Dielectric Constant at 100 Hz		2.85
Dielectric Constant at 100 kHz		2.79
Dissipation Factor at 100 Hz		0.008
Dissipation Factor at 100 kHz		0.002
Linear CTE (by DMA)	µm/m- °C or ppm	300

Description

Dow's SYLGARD™ silicone 1 to 1 encapsulants are supplied as two-part liquid component kits. When liquid components are thoroughly mixed, the mixture cures to a flexible elastomer, which is well suited for the protection of electrical and PCB system assembly applications. SYLGARD™ silicone encapsulants cure without exotherm at a constant rate regardless of sectional thickness or degree of confinement.

SYLGARD™ silicone elastomers require no post cure and can be placed in service immediately following the completion of the cure schedule. Standard silicone encapsulants may require a surface treatment with a primer in addition to good cleaning for adhesion while primerless silicone encapsulants require only good cleaning.

Application Methods

- Automated metered mixing and dispensing
- Manual mixing

Mixing and De-Airing

These products are supplied in a 1 to 1 mix ratio, which is very robust in manufacturing environments and allows for some process and dispense equipment variation. In most cases de-airing is not required.

Preparing Surfaces

In applications requiring good adhesion, priming may be required for many of the silicone encapsulants which are "non-primerless". For best results, the primer should be applied in a very thin, uniform coating and then wiped off after application. After application, it should be thoroughly cured prior to application of the silicone elastomer. Additional instructions for primer usage can be found in the information sheets specific to the individual primers.

Processing/Curing

Thoroughly mixed SYLGARD™ silicone encapsulant may be poured/dispensed directly into the container in which it is to be cured. Care should be taken to minimize air entrapment. When practical, pouring/dispensing should be done under vacuum, particularly if the components being potted or encapsulated have many small voids. If this technique cannot be used, the unit should be evacuated after the silicone encapsulant has been poured/dispensed. SYLGARD™ silicone encapsulants may be either room temperature (25°C/77°F) or heat cured. Room temperature cure encapsulants may also be heat accelerated for faster cure. Ideal cure conditions for each product are given in the product selection table. Two-part condensation cure encapsulants should not be heat accelerated above 60°C (140°F).

Pot Life and Cure Rate

Cure reaction begins with the mixing process. Initially, cure is evidenced by a gradual increase in viscosity, followed by gelation and conversion to a solid elastomer. Pot life is defined as the time required for viscosity to double after Parts A and B (base and curing agent) are mixed and is highly temperature and application dependent. Please refer to the data table.

Useful Temperature Ranges

For most uses, silicone elastomers should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low- and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations and should be adequately tested for the particular end use environment. For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

Compatibility

Certain materials, chemicals, curing agents and plasticizers can inhibit the cure of addition cure gels. Most notable of these include: organotin and other organometallic compounds, silicone rubber containing organotin catalyst, sulfur, polysulfides, polysulfones or other sulfur containing materials, unsaturated hydrocarbon plasticizers, and some solder flux residues. If a substrate or material is questionable with respect to potentially causing inhibition of cure, it is recommended that a small scale compatibility test be run to ascertain suitability in a given application. The presence of liquid or uncured product at the interface between the questionable substrate and the cured gel indicates incompatibility and inhibition of cure.

Repairability

In the manufacture of electrical devices and PCB system assemblies it is often desirable to salvage or reclaim damaged or defective units. With most non-silicone rigid potting/encapsulating materials, removal or entry is difficult or impossible without causing excessive damage to internal circuitry. SYLGARD™ silicone encapsulants can be selectively removed with relative ease, depending on the chosen remove method and technique and repairs or changes accomplished, and the repaired area repotted in place with additional product. To remove silicone elastomers, simply cut with a sharp blade or knife and tear and remove unwanted material from the area to be repaired. Sections of the adhered elastomer are best removed from substrates and circuitry by mechanical action such as scraping or rubbing and can be assisted by applying Dow OS fluids to swell the elastomer. Before applying additional encapsulant to a repaired device, roughen the exposed surfaces of the cured encapsulant with an abrasive paper and rinse with a suitable solvent and dry. This will enhance adhesion and permit the repaired material to become an integral matrix with the existing encapsulant. Silicone prime coats are not recommended for adhering products to themselves.

**Handling
Precautions**

PRODUCT SAFETY INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE SAFETY DATA SHEET IS AVAILABLE ON THE DOW WEBSITE AT DOW.COM, OR FROM YOUR DOW SALES APPLICATION ENGINEER, OR DISTRIBUTOR, OR BY CALLING DOW CUSTOMER SERVICE.

**Usable Life and
Storage**

Shelf life is indicated by the "Use Before" date found on the product label. Refer to the product label for storage temperature requirements. Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen. Exposure to moisture could reduce adhesion and cause bubbles to form. Encapsulant materials which contain higher levels of fillers that have been stored for long periods of time should typically be agitated or rolled prior to mixing to prevent separation and settle-out.

**Packaging
Information**

Multiple packaging sizes are available for this product.

Limitations

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

**Health and
Environmental
Information**

To support customers in their product safety needs, Dow has an extensive Product Stewardship organization and a team of product safety and regulatory compliance specialists available in each area.

For further information, please see our website, dow.com or consult your local Dow representative.

**Disposal
Considerations**

Dispose in accordance with all local, state (provincial) and federal regulations. Empty containers may contain hazardous residues. This material and its container must be disposed in a safe and legal manner.

It is the user's responsibility to verify that treatment and disposal procedures comply with local, state (provincial) and federal regulations. Contact your Dow Technical Representative for more information.

**Product
Stewardship**

Dow has a fundamental concern for all who make, distribute, and use its products, and for the environment in which we live. This concern is the basis for our product stewardship philosophy by which we assess the safety, health, and environmental information on our products and then take appropriate steps to protect employee and public health and our environment. The success of our product stewardship program rests with each and every individual involved with Dow products - from the initial concept and research, to manufacture, use, sale, disposal, and recycle of each product.

Customer Notice

Dow strongly encourages its customers to review both their manufacturing processes and their applications of Dow products from the standpoint of human health and environmental quality to ensure that Dow products are not used in ways for which they are not intended or tested. Dow personnel are available to answer your questions and to provide reasonable technical support. Dow product literature, including safety data sheets, should be consulted prior to use of Dow products. Current safety data sheets are available from Dow.

How Can We Help You Today?

Tell us about your performance, design, and manufacturing challenges. Let us put our silicon-based materials expertise, application knowledge, and processing experience to work for you.

For more information about our materials and capabilities, visit **dow.com**.

To discuss how we could work together to meet your specific needs, go to **dow.com** for a contact close to your location. Dow has customer service teams, science and technology centers, application support teams, sales offices, and manufacturing sites around the globe.

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